EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	0	("10798540").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:43
S2	228	(conductive adj contact adj pad) and (dielectric) and (regions)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 18:09
S3	11	(conductive adj contact adj pad) and (dielectric) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 18:13
S4	260	(contact adj pad) and (dielectric) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:45
S5	503	(contact adj pad) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 19:54
S6	0	S5 and ((solder near paste) with (opening and via and trench))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 19:56
S7	47	S5 and ((solder near paste) with (opening via trench))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:28
S8	503	(contact adj pad) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:29

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S9	28	S8 and ((solder near paste) and (second adj substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:30
S10	65	(contact adj pad) and (dielectric) and (solder near paste) and (second adj substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:34
S11	49	S10 and openings	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:35
S12	185	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:47
S13	5194150	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated circuit) or (integrated circuit package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:48
S14	185	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated circuit) and (integrated circuit package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:50
S15	131	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated adj circuit) and (integrated circuit package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:50
S16	2	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated adj circuit) and (integrated adj circuit adj package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:51

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S17	28312	flip adj chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:44
S19	825	S17 and (contact adj pads) and dielectric and openings	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 18:47
S20	18	S19 and (solder adj paste) with (opening via trench hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:46
S21	548	S19 and (integrated adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:48
S22	82	S21 and (solder near2 (wet wettable))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:49
S23	2	("6322903").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 18:41
S27	776	S17 and (bond adj pads) and dielectric and openings	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 18:48
S28	3220	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/27 15:47

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S29	10712	(contact adj pad) and (dielectric or insulat$5) and (opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 13:21
S30	4265	S29 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 13:22
S31	2627	S30 and (integrated adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:27
S32	10725	(contact adj pad) and (dielectric or insulat$5) and (opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:27
S33	4269	S32 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:27
S34	2630	S33 and (integrated adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:27
S35	1312	S34 and (flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:27
S36	2	("4256532" | "5880017").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/04 15:39
S37	2	("5341564" | "5952718").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/18 10:48

| S38 | 20 | ("2014524" \| "2774747" \| "3401126" \| "3429040" \| "4113981" \| "4442966" \| "5046415" \| "5056296" \| "5074947" \| "5196371" \| "5237130" \| "5539153" \| "5611140" \| "5667884" \| "5879761" \| "5924622").PN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2006/04/18 12:38 |